Reliability Data Report
Report Number: R541

Report generated on: Thu Dec 12 10:40:19 PST 2013

OPERATING LIFE TEST

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C)[1]	No. of FAILURES[2,3]
QFN/DFN	308	0826	1005	269	0
Totals	308	-	-	269	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	396	0912	1303	32	0
SOIC/SOT/MSOP	98	0937	1005	4	0
Totals	494	-	-	36	0

TEMP CYCLE FROM -65 TO 150 DEG C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	296	0914	1303	29	0
SOIC/SOT/MSOP	50	1005	1005	5	0
Totals	346	-	-	34	0

THERMAL SHOCK FROM -65 TO 150 DEG C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	677	0912	1303	335	0
SOIC/SOT/MSOP	100	0937	1005	10	0
Totals	777	-	-	345	0

(1) Assumes Activation Energy = 1.0 Electron Volts
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =6.81 FITS
(3) Mean Time Between Failure in Years = 16750.93
Note: 1 FIT = 1 Failure in One Billion Hours.
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL1 Preconditioning